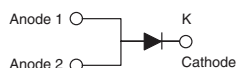
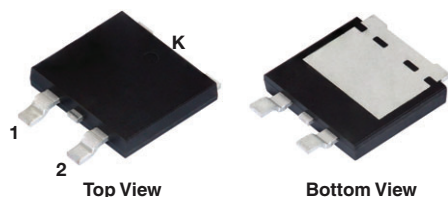


# Dual High-Voltage TMBS® (Trench MOS Barrier Schottky) Rectifier

Ultra Low  $V_F = 0.46 \text{ V}$  at  $I_F = 5 \text{ A}$

## eSMP® Series SMPD (TO-263AC)



## FEATURES

- Trench MOS Schottky technology generation 2
- Very low profile - typical height of 1.7 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available  
- Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

AUTOMOTIVE  
GRADE  
Available



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## LINKS TO ADDITIONAL RESOURCES



## TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	30 A
$V_{RRM}$	120 V
$I_{FSM}$	250 A
$V_F$ at $I_F = 30 \text{ A}$ ( $T_A = 125 \text{ °C}$ )	0.73 V
$T_J$ max.	175 °C
Package	SMPD (TO-263AC)
Circuit configuration	Single

## MECHANICAL DATA

**Case:** SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and

AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

**Polarity:** as marked

## MAXIMUM RATINGS ( $T_A = 25 \text{ °C}$ unless otherwise noted)

PARAMETER	SYMBOL	V30DM120	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	120	V
Maximum average forward rectified current (fig. 1)	$I_{F(AV)}^{(1)}$	30	A
	$I_{F(AV)}^{(2)}$	6	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	250	A
Operating junction and storage temperature range	$T_J, T_{STG}$	-40 to +175	°C

## Notes

(1) With infinite heatsink

(2) With recommended pad size, 2 oz FR4 PCB

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	I <sub>F</sub> = 5 A	T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.55	-	V
	I <sub>F</sub> = 15 A			0.73	-	
	I <sub>F</sub> = 30 A			0.98	1.06	
	I <sub>F</sub> = 5 A	T <sub>A</sub> = 125 °C		0.46	-	
	I <sub>F</sub> = 15 A			0.61	-	
	I <sub>F</sub> = 30 A			0.73	0.81	
Reverse current at rated V <sub>R</sub> per diode	V <sub>R</sub> = 90 V	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	0.01	-	mA
		T <sub>A</sub> = 125 °C		4	-	
	V <sub>R</sub> = 120 V	T <sub>A</sub> = 25 °C		-	1	
		T <sub>A</sub> = 125 °C		8	20	

**Notes**(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle(2) Pulse test: Pulse width  $\leq 5\text{ ms}$ **THERMAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

PARAMETER	SYMBOL	V30DM120	UNIT
Typical thermal resistance	$R_{\theta JC}$	1.2	$^{\circ}\text{C/W}$
	$R_{\theta JA}^{(1)(2)}$	48	

**Notes**(1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$  - junction-to-mount

(2) Free air, without heatsink

**ORDERING INFORMATION** (Example)

PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V30DM120-M3/I	0.55	I	2000/reel	13" diameter plastic tape and reel
V30DM120HM3/I <sup>(1)</sup>	0.55	I	2000/reel	13" diameter plastic tape and reel

**Note**

(1) AEC-Q101 qualified

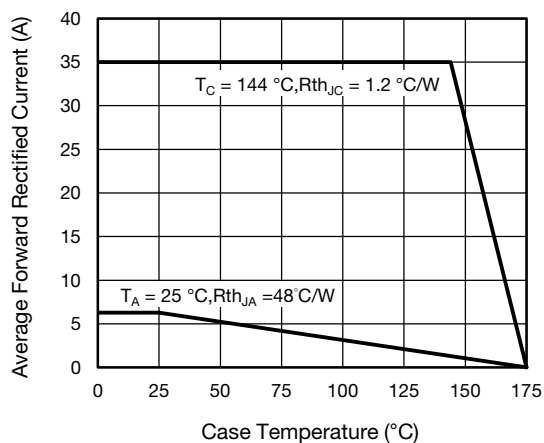
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Forward Current Derating Curve

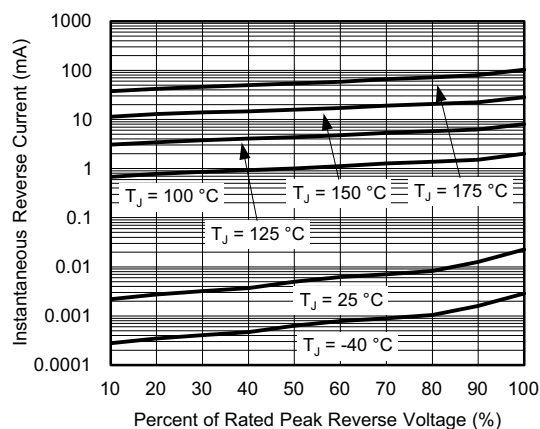


Fig. 4 - Typical Reverse Characteristics

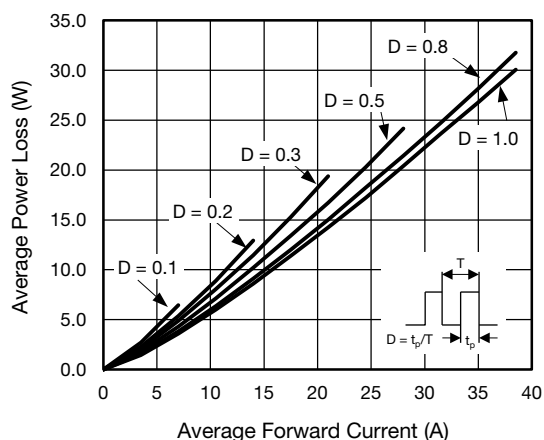


Fig. 2 - Forward Power Loss Characteristics

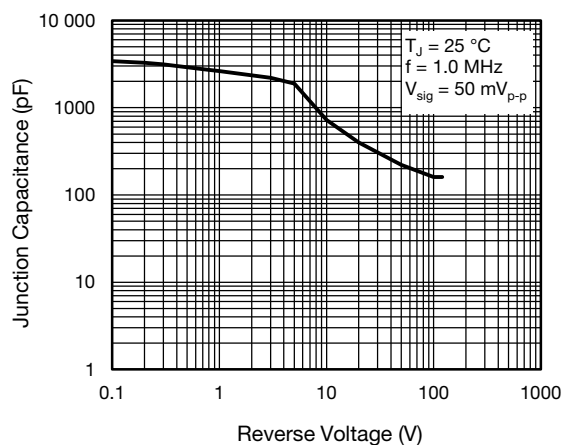


Fig. 5 - Typical Junction Capacitance

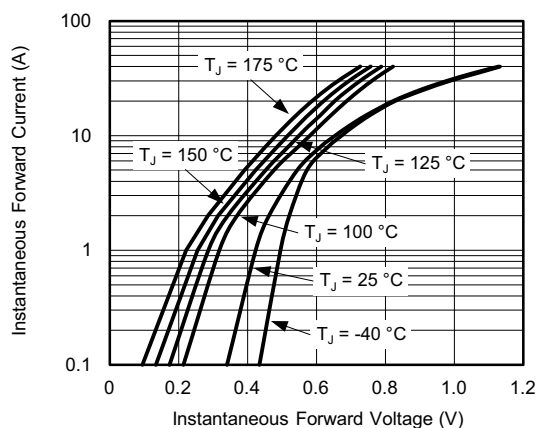


Fig. 3 - Typical Instantaneous Forward Characteristics

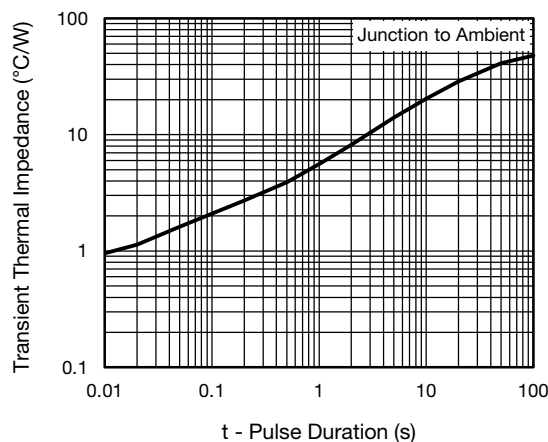


Fig. 6 - Typical Transient Thermal Impedance

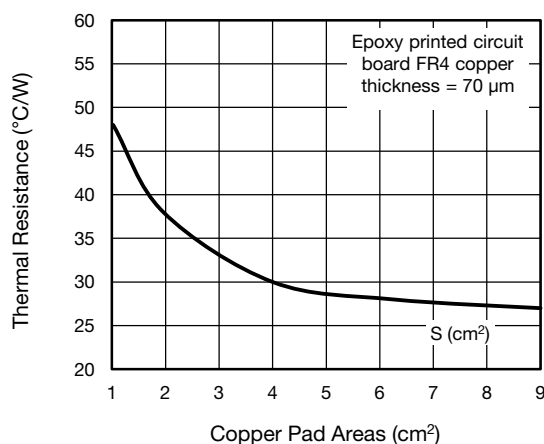
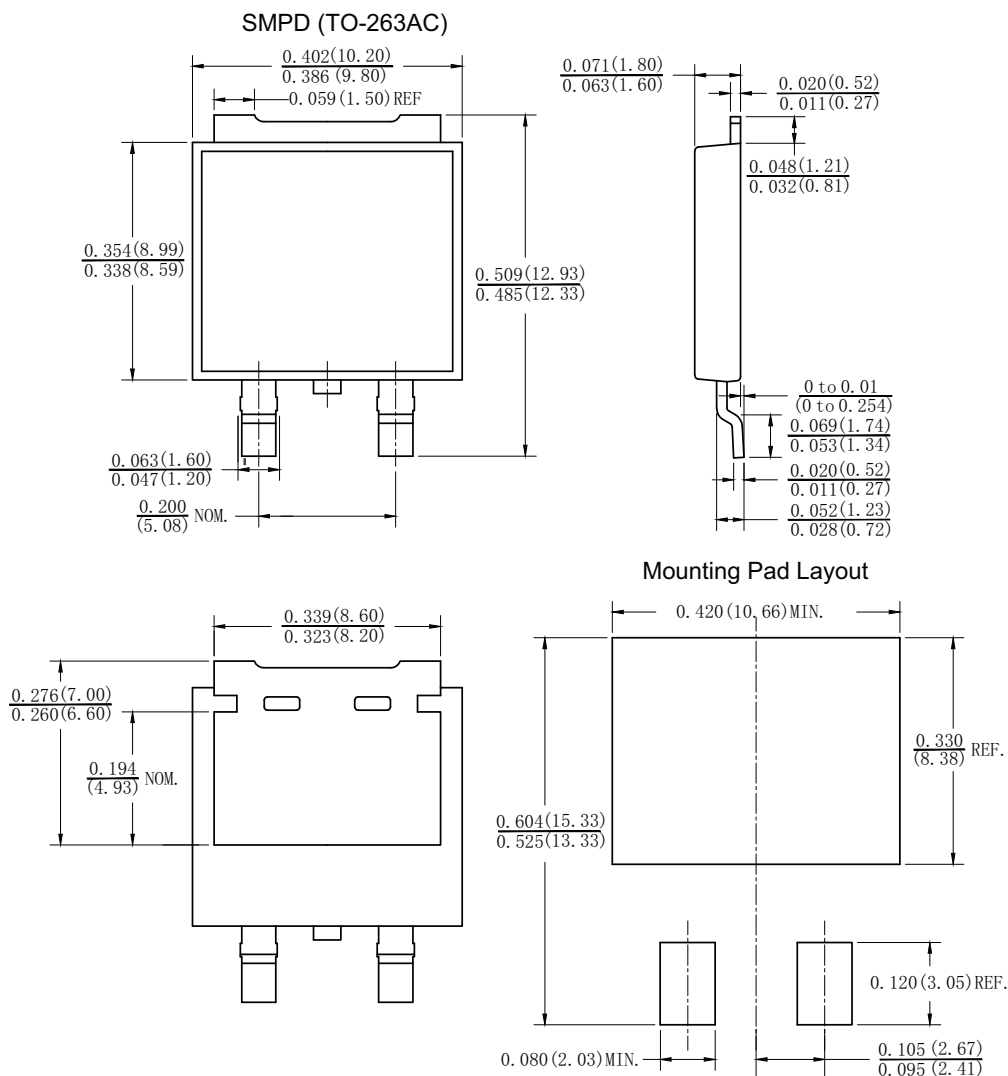


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)




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